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01-december-2011

Polprevodniški elementi - Metode za mehanske in klimatske preskuse - 40. del: Preskusna metoda s padcem z mizne višine z uporabo tenzometra

Semiconductor devices - Mechanical and climatic test methods - Part 40: Board level drop test method using a strain gauge

Halbleiterbauelemente - Mechanische und klimatische Prüfverfahren - Teil 40: Prüfverfahren zum Fall einer Leiterplatte unter Verwendung von Dehnungsmessstreifen

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Dispositifs à semiconducteurs - Méthodes d'essais mécaniques et climatiques - Partie 40: Méthode d'essai de chute au niveau de la carte avec utilisation d'une jauge de contrainte

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ICS:

31.080.01	Polprevodniški elementi (naprave) na splošno	Semiconductor devices in general

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EUROPEAN STANDARD

NORME EUROPÉENNE

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EN 60749-40

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English version

Semiconductor devices - Mechanical and climatic test methods - Part 40: Board level drop test method using a strain gauge (IEC 60749-40:2011)

Dispositifs à semiconducteurs - Méthodes d'essais mécaniques et climatiques - Partie 40: Méthode d'essai de chute au niveau de la carte avec utilisation d'une jauge de contrainte (CEI 60749-40:2011)

Halbleiterbauelemente - Mechanische und klimatische Prüfverfahren - Teil 40: Prüfverfahren zum Fall einer Leiterplatte unter Verwendung von Dehnungsmessstreifen (IEC 60749-40:2011)

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Foreword

The text of document 47/2094/FDIS, future edition 1 of IEC 60749-40, prepared by IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60749-40 on 2011-08-17.

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The following dates were fixed:

– latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement	(dop)	2012-05-17
– latest date by which the national standards conflicting with the EN have to be withdrawn	(dow)	2014-08-17

Annex ZA has been added by CENELEC.

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Annex ZA
(normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

Publication	Year	Title	EN/HD	Year
IEC 60749-37	-	Semiconductor devices - Mechanical and climatic test methods - Part 37: Board level drop test method using an accelerometer	EN 60749-37	-

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**Semiconductor devices – Mechanical and climatic test methods –
Part 40: Board level drop test method using a strain gauge**

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**Dispositifs à semiconducteurs – Méthodes d'essais climatiques et mécaniques –
Partie 40: Méthode d'essai de chute au niveau de la carte avec utilisation d'une jauge de contrainte**

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SEMICONDUCTOR DEVICES –
MECHANICAL AND CLIMATIC TEST METHODS –

Part 40: Board level drop test method using a strain gauge

FOREWORD

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47/2094/FDIS	47/2100/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

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This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of the IEC 60749 series, under the general title *Semiconductor devices – Mechanical and climatic test methods*, can be found in the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

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